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Part Number: [73780-0253](#)
Status: **Active**
Overview: [HDM®](#)
Description: 2.00mm Pitch HDM® Board-to-Board Daughtercard Receptacle, Vertical, Signal Module, 72 Circuits, Mounted Height 13.00mm, Pin Length 3.50mm, Soder Tail

Documents:

[3D Model](#) [Test Summary TS-73670-990 \(PDF\)](#)
[Drawing \(PDF\)](#) [RoHS Certificate of Compliance \(PDF\)](#)
[Product Specification PS-73780-999 \(PDF\)](#)

General

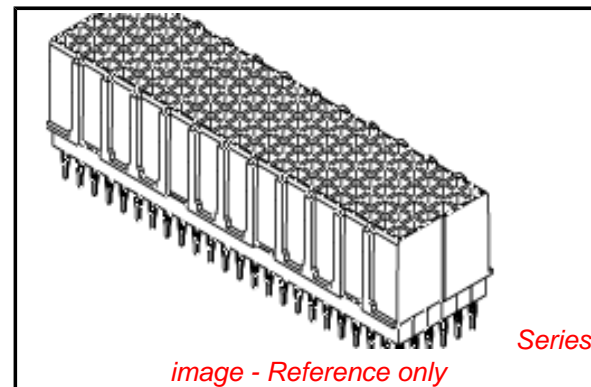
Product Family	Backplane Connectors
Series	73780
Application	Daughtercard, Mezzanine
Comments	Solder Tail
Component Type	PCB Receptacle
Overview	HDM®
Product Name	HDM®
Style	N/A
UPC	756054405895

Physical

Circuits (Loaded)	72
Circuits (maximum)	72
Color - Resin	Black
Durability (mating cycles max)	250
First Mate / Last Break	No
Guide to Mating Part	No
Keying to Mating Part	None
Material - Metal	Copper-Nickel-Tin
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	High Temperature Thermoplastic
Net Weight	10.002/g
Number of Columns	12
Number of Pairs	Open Pin Field
Number of Rows	6
Orientation	Vertical
PC Tail Length	3.50mm
PCB Locator	No
PCB Retention	None
PCB Thickness - Recommended	1.60mm
Packaging Type	Tube
Pitch - Mating Interface	2.00mm
Pitch - Termination Interface	2.00mm
Plating min - Mating	0.762µm
Plating min - Termination	2.540µm
Polarized to PCB	No
Stackable	Yes
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole

Electrical

Current - Maximum per Contact	15A, 1A
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EU RoHS

**ELV and RoHS
Compliant**

REACH SVHC

**Contains SVHC: No
Low-Halogen Status
Low-Halogen**

China RoHS



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environmental compliance?**

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

[73780Series](#)

Mates With

HDM® Board-to-Board Backplane Header
[73642](#) , [73643](#) , [73644](#) , [73942](#) , [73943](#) ,
[73944](#) , [74349](#) , [74428](#). HDM® Board-to-
Board Stacking Header [73769](#) , [73770](#) ,
[73782](#) , [73783](#) , [73771](#)

Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Solder Process Data

Duration at Max. Process Temperature (seconds)	5
Lead-free Process Capability	Wave Capable (TH only)
Max. Cycles at Max. Process Temperature	1
Process Temperature max. C	260

Material Info

Reference - Drawing Numbers

Product Specification	PS-73780-999
Sales Drawing	SD-73780-004
Test Summary	TS-73670-990

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This document was generated on 10/05/2012

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